

Features:

- High luminous LEDs
- 5mm round standard directivity
- Superior weather-resistance
- UV Resistant epoxy
- Water clear type

Applications

- Electronic Signs and Signals
- Small Area Illuminations
- Back Lighting
- Other Lighting

Absolute maximum rating (Ta=25°C)

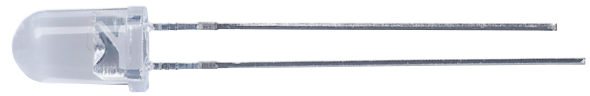
Item	Symbol	Value	Unit
DC forward current	I_F	30	mA
Pulse forward current*	I_{FP}	100	mA
Reverse voltage	V_R	5	V
Power dissipation	P_D	78	mW
Operating temperature	T_{opr}	-30 to +85	°C
Storage temperature	T_{stg}	-40 to +100	°C
Lead soldering temperature	T_{sol}	260°C/5 sec	-

*Pulse width max. 10ms. Duty ratio max. 1/10

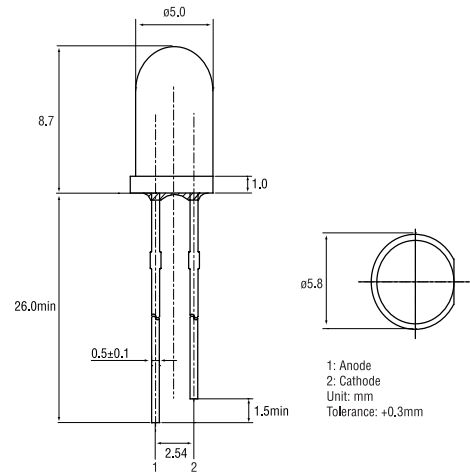
Electrical - Optical characteristics (Ta=25°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
DC Forward voltage	V_F	$I_F = 20\text{mA}$	1.8	2.1	2.6	V
DC Reverse current	I_R	$V_R = 5\text{V}$	-	-	10	μA
Domi. Wavelength*	λ_D	$I_F = 20\text{mA}$	585	590	595	nm
Luminous intensity†	I_V	$I_F = 20\text{mA}$	4200	5800	7000	mcd
50% Power angle	$2\theta_{1/2}$	$I_F = 20\text{mA}$	-	15	-	deg

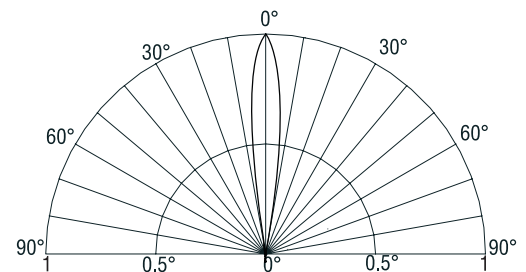
* Tolerance of dominant wavelength is $\pm 1\text{nm}$
 † Tolerance of luminous intensity is $\pm 15\%$



Outline dimensions:

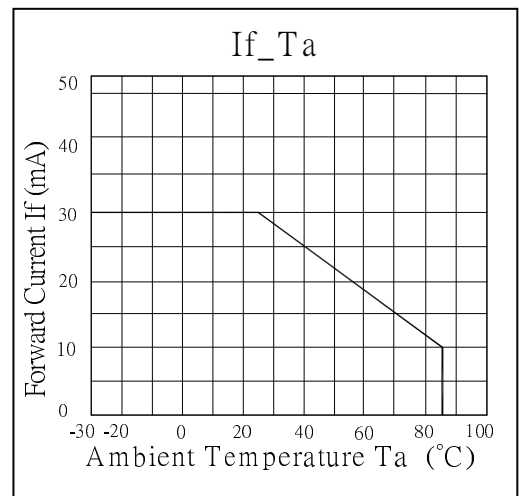
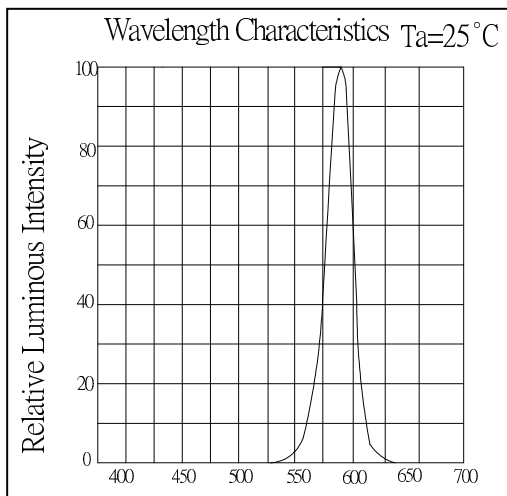
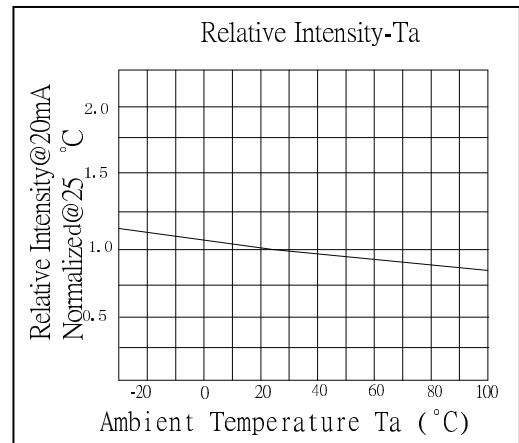
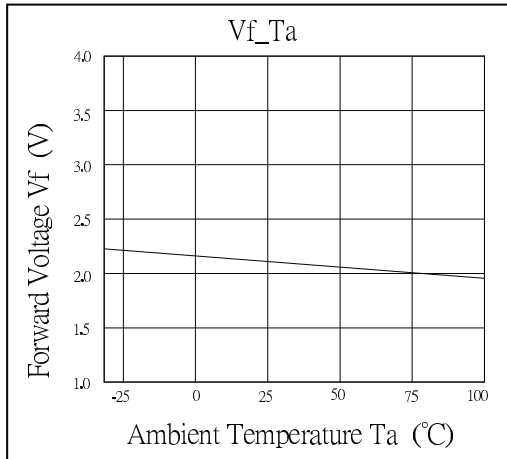
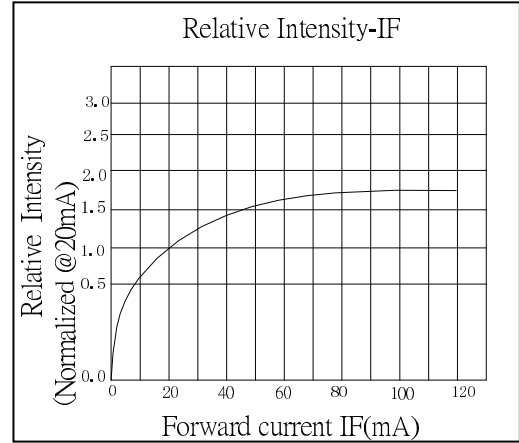
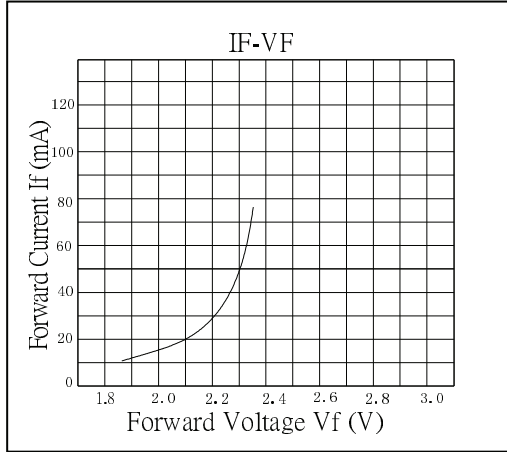


Directivity:



AlGaInP LED

TYPICAL ELECTRICAL/OPTICAL CHARACTERISTIC CURVES



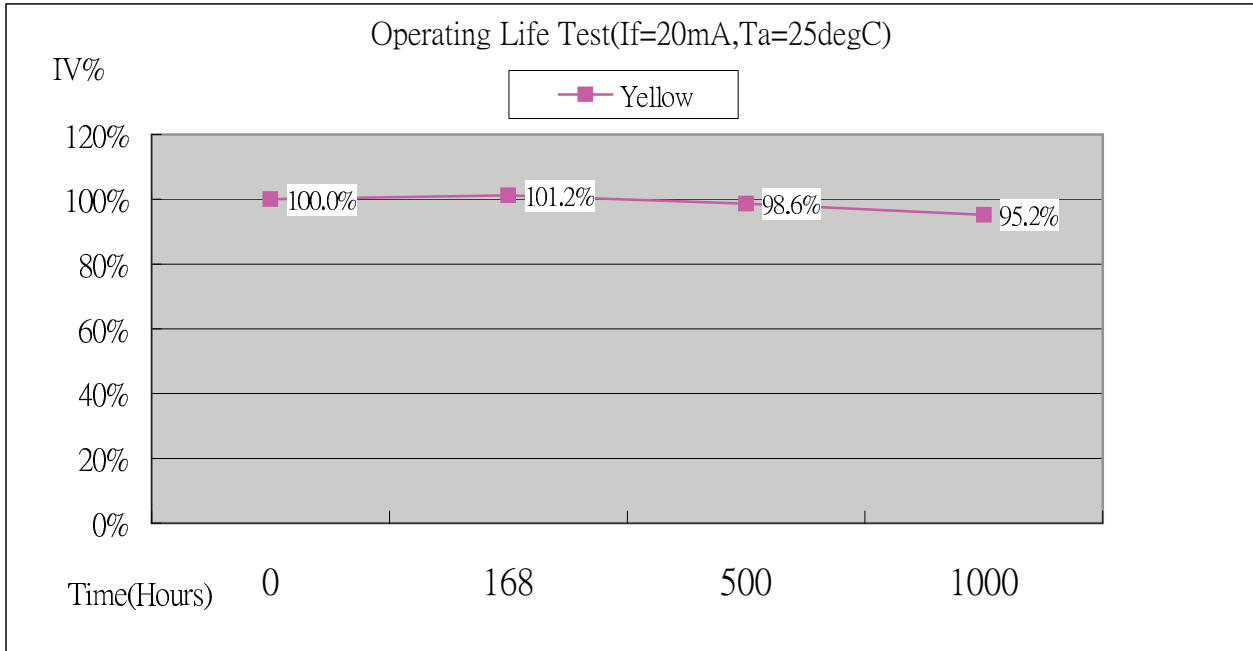
RELIABILITY TEST REPORT

CLASSIFICATION	TEST ITEM	TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	If:20mA Ta:25+5 TEST TIME=1000HRS (-24HRS,+72HRS)
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	R.H:90~95% Ta:65+5°C TEST TIME=240HRS (+2HRS)
	HIGH TEMPERATURE STORAGE	Ta:105±5°C TEST TIME=500HRS (-24HRS,+48HRS)
	LOW TEMPERATURE STORAGE	Ta:-55±5°C TEST TIME=500HRS (-24HRS,+48HRS)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	105°C~25°C~-55°C~25°C 60min 10min 60min 10min 20cycles
	THERMAL SHOCK	105°C~-55°C 10min 10min 10cycles
	SOLDER RESISTANCE	Ta:260±5°C TEST TIME=10±1sec
	SOLDERABILITY	Ta:230±5°C TEST TIME=5±1sec

JUDGMENT CRITERIA OF FAILURE FOR THE RELIABILITY

MEASURING TIME	SYMBOL	CONDITIONS	FAILURE
LUMINOUS INTENSITY	IV	If=20mA	IV<0.5*INITIAL VALUE
FORWARD VOLTAGE	VF	If=20mA	VF>1.2*INITIAL VALUE
REVERSE CURRENT	IR	Vr=5V	IR>2*SPEC

RELIABILITY TEST REPORT



* Burn-in condition: 20mA

* Projection of Statistical Average Light Output Degradation Performance for LED Technology Extrapolated from TruOpto QA Dept. Test Data.

* According to TruOpto outgoing Packaged Products Specification

* MTBF:50,000hrs, 90% Confidence (A Failure is Any LED Which is Open, shorted or fails to Emit Light)

* The Projected Data is Base on The Feature of LED Itself Under Normal Operation Conditions.

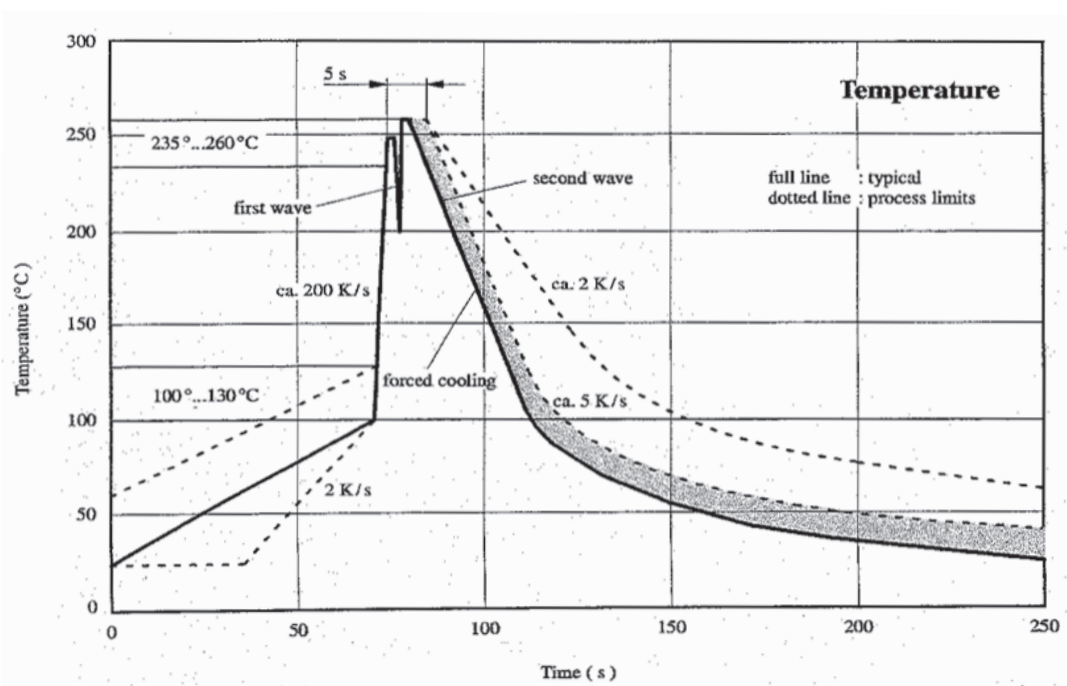
* Any Improper Circuit Design or External Factors Might Cause a Different Result.

LAMP APPLICATION (PB FREE SOLDERING)

Apply to LAMP (DIP) SERIES

Description:

- (1) Manual soldering (Solder Iron)
 - (1.1) Temperature at tip of the iron: 300 °C Max.
 - (1.2) It's banned to load any stress on the resin during soldering.
 - (1.3) Soldering time: 3sec. Max. (one time only.)
 - (1.4) Leave 3mm of minimum distance from the base of the epoxy.
- (2) Dip Soldering (Wave Soldering-Solder Bath)
 - (2.1) Leave 3mm of minimum distance from the base of the epoxy. Soldering beyond the base of the tie bar (stand off) is recommended.
 - (2.2) When soldering, do not put stress on the LEDs during heating.
 - (2.3) Cutting the lead frames at high temperatures may cause LED failure.
 - (2.4) Never take next process until the component is cooled down to room temperature after reflow.
 - (2.5) After soldering, do not warp the circuit board.
 - (2.6) The recommended dip soldering profile is the following.



Wave soldering of double wave optodevices